Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

MICROCHIP Semiconductor Device Type: YM5 (6BX) 005 SOT-23 NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609 Product Marking and/or Pkg. Labeling e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	8.40	(mg) Total	Mold Compound	% ot Total Weight	48.28
Silica, vitreous (or fused)	60676-86-0	Mold Compound	41.038	7.141	410,380		Silica, vitreous (or fused)	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	4.200	0.731	42.004	ł	Epoxy Resin	Trade Secret	8.70	
Phenolic Resin	Trade Secret	Mold Compound	2.897	0.504	28.968	ł	Phenolic Resin	Trade Secret	6.00	
Carbon Black	1333-86-4	Mold Compound	0.145	0.025	1,448	ł	Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	47.045	8.186	470,446	ł		Total	100.00	
Iron	7439-89-6	Lead Frame	1.112	0.193	11.121	8.41	(mm) Total			48.35
						8.41	(mg) Total	Lead Frame	% of Total Weight	48.35
Phosphorous	7723-14-0	Lead Frame	0.121	0.021	1,209	l	Copper	7440-50-8	97.30	
Zinc (Metal)	7440-66-6	Lead Frame	0.073	0.013	725	l	Iron	7439-89-6	2.30	
Aluminum oxide	1344-28-1	Die Attach	0.122	0.021	1,221		Phosphorous	7723-14-0	0.25	
Bisphenol A, epichlorohydrin polymer	25068-38-6	Die Attach	0.122	0.021	1,221		Zinc (Metal)	7440-66-6	0.15	
Epoxy resin	25036-25-3	Die Attach	0.122	0.021	1,222			Total	100.00	
Amine modified epoxy isocyanate resin	Trade Secret	Die Attach	0.034	0.006	336	0.07	(mg) Total	Die Attach	% of Total Weight	0.40
Silicon	7440-21-3	Chip (Die)	1.080	0.188	10,800		Aluminum oxide	1344-28-1	30.53	
Gold	7440-57-5	Wire Bond	0.150	0.026	1,500	Bisphenol	A, epichlorohydrin polymer	25068-38-6	30.53	
Nickel	7440-02-0	Plating on external leads (pins)	1.566	0.272	15,660	1	Epoxy resin	25036-25-3	30.54	
	7440.05.0	Plating on external leads (pins)	0.087	0.015	870	Amine modi	fied epoxy isocyanate resin	Trade Secret	8.40	
Palladium	7440-05-3	rialing on external leads (pins)								
Palladium Gold	7440-05-3	Plating on external leads (pins)	0.087	0.015	870		ned openy receyand to recin	Total	100.00	
		Plating on external leads (pins)	0.087		870 1.000.000			Total		1.08
Gold	7440-57-5 0.0174 aterials comply with	Plating on external leads (pins) TOTALS: g Total Mass h EU Directives: 2002/95/EC (27 January 2003)	0.087 100.000	0.015 17.400	1,000,000	0.19	Total (mg) Doped Silicon		100.00 % of Total Weight 100.00 100.00	1.08
Gold semiconductor device and its homogenous m 363/EU (31 March 2015) and 2002/53/EC (End-	7440-57-5 0.0174 aterials comply wit- of-Life Vehicles (E	Plating on external leads (pins) TOTALS: g Total Mass h EU Directives: 2002/95/EC (27 January 2003)	0.087 100.000 & Directive 201	0.015 17.400 1/65/EU (08 Ju	1,000,000		Total (mg)	Total Chip (Die) 7440-21-3	% of Total Weight 100.00	0.15
Gold semiconductor device and its homogenous m 363/EU (31 March 2015) and 2002/53/EC (End- diance with the above EU Directives has been semical substance is absent from the list above thip Technology Incorporated's knowledge a	7440-57-5 0.0174 aterials comply wit- of-Life Vehicles (E- verified via internate, the chemical sund belief as of the	Plating on external leads (pins) TOTALS: g Total Mass h EU Directives: 2002/95/EC (27 January 2003) LV) without exemption (zero)	0.087 100.000 & Directive 201* r analytical test of semiconductor of the believe that	0.015 17.400 1/65/EU (08 Judata. device and, to the the unavoida	1,000,000 une 2011) and the best of	0.19	Total (mg) Doped Silicon	Total Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	
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